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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

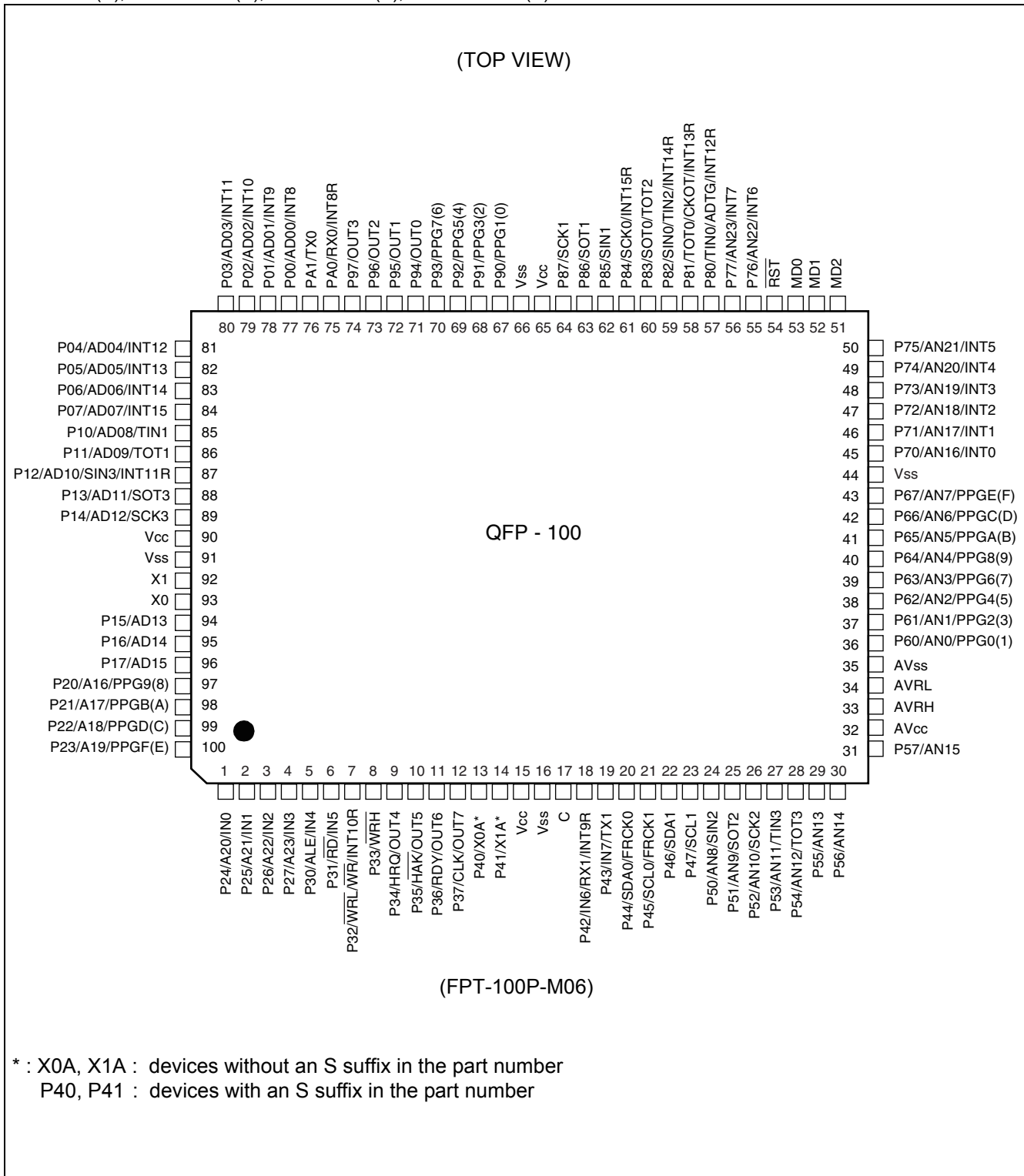
Details

Product Status	Obsolete
Core Processor	F ² MC-16LX
Core Size	16-Bit
Speed	24MHz
Connectivity	CANbus, EBI/EMI, LINbus, SCI, UART/USART
Peripherals	DMA, POR, WDT
Number of I/O	82
Program Memory Size	128KB (128K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	A/D 16x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90347espmc-gs-494e1

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■ MB90341CE(S), MB90342CE(S), MB90F342CE(S), MB90F345CE(S), MB90346CE(S), MB90F346CE(S), MB90347CE(S), MB90F347CE(S), MB90348CE(S), MB90349CE(S), MB90F349CE(S)



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Pin No.		Pin name	I/O Circuit type*3	Function
QFP100*1	LQFP100*2			
9	7	P34	G	General purpose I/O pin. The register can be set to select whether to use a pull-up resistor. This function is enabled either in single-chip mode or when the hold function is disabled.
		HRQ		Hold request input pin. This function is enabled when both the external bus and the hold function are enabled.
		OUT4		Waveform output pin for output compare.
10	8	P35	G	General purpose I/O pin. The register can be set to select whether to use a pull-up resistor. This function is enabled either in single-chip mode or when the hold function is disabled.
		$\overline{\text{HAK}}$		Hold acknowledge output pin. This function is enabled when both the external bus and the hold function are enabled.
		OUT5		Waveform output pin for output compare.
11	9	P36	G	General purpose I/O pin. The register can be set to select whether to use a pull-up resistor. This function is enabled either in single-chip mode or when the external ready function is disabled.
		RDY		External ready input pin. This function is enabled when both the external bus and the external ready function are enabled.
		OUT6		Waveform output pin for output compare.
12	10	P37	G	General purpose I/O pin. The register can be set to select whether to use a pull-up resistor. This function is enabled either in single-chip mode or when the clock output is disabled.
		CLK		Clock output pin. This function is enabled when both the external bus and clock output are enabled.
		OUT7		Waveform output pin for output compare
13, 14	11, 12	P40, P41	F	General purpose I/O pins. (devices with an S suffix in the part number and or MB90V340E-101)
		X0A, X1A	B	Oscillation pins for sub clock (devices without an S suffix in the part number and or MB90V340E-102)
15	13	V _{CC}	—	Power (3.5 V to 5.5 V) input pin
16	14	V _{SS}	—	GND pin
17	15	C	K	This is the power supply stabilization capacitor This pin should be connected to a ceramic capacitor with a capacitance greater than or equal to 0.1 μF .
18	16	P42	F	General purpose I/O pin.
		IN6		Trigger input pin for input capture.
		RX1		RX input pin for CAN1 Interface (MB90341E/342E/F342E/F345E only)
		INT9R		External interrupt request input pin

(Continued)

5. Handling Devices

1. Preventing latch-up

CMOS IC may suffer latch-up under the following conditions:

- A voltage higher than V_{CC} or lower than V_{SS} is applied to an input or output pin.
- A voltage higher than the rated voltage is applied between V_{CC} and V_{SS} pins.
- The AV_{CC} power supply is applied before the V_{CC} voltage.

Latch-up may increase the power supply current drastically, causing thermal damage to the device.

For the same reason, also be careful not to let the analog power-supply voltage (AV_{CC} , AV_{RH}) exceed the digital power-supply voltage.

2. Handling unused pins

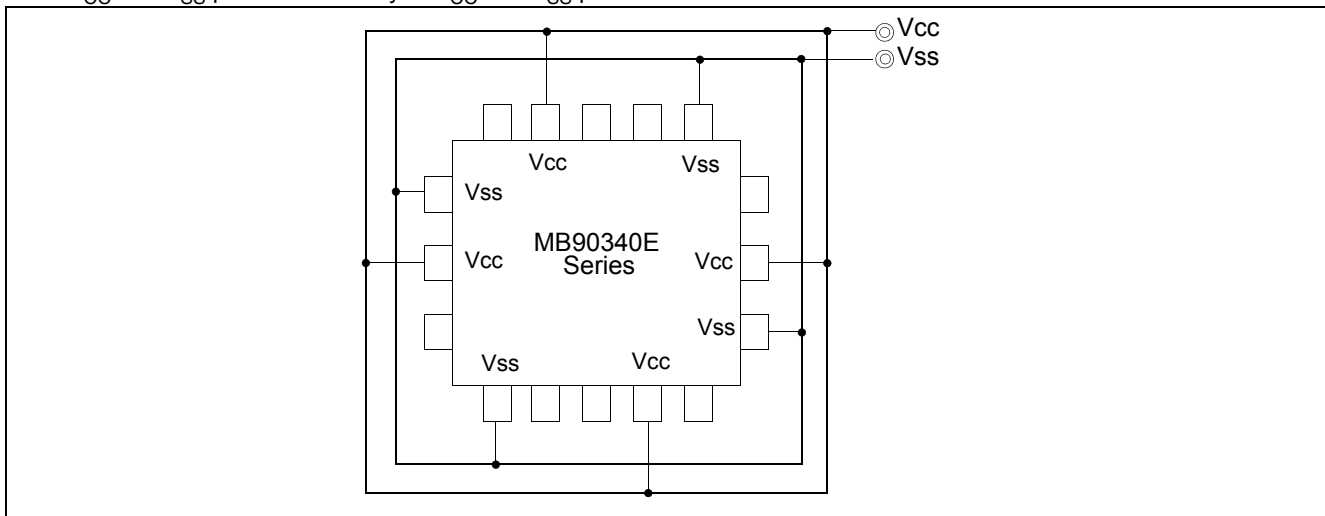
Leaving unused input terminals open may lead to permanent damage due to malfunction and latch-up; pull up or pull down the terminals through the resistors of 2 k Ω or more.

3. Power supply pins (V_{CC}/V_{SS})

- If there are multiple V_{CC} and V_{SS} pins, from the point of view of device design, pins to be of the same potential are connected inside of the device to prevent malfunction such as latch-up.

To reduce unnecessary radiation, prevent malfunctioning of the strobe signal due to the rise of ground level, and observe the standard for total output current, be sure to connect the V_{CC} and V_{SS} pins to the power supply and ground externally. Connect V_{CC} and V_{SS} pins to the device from the current supply source at a possibly low impedance.

- As a measure against power supply noise, it is recommended to connect a capacitor of about 0.1 μ F as a bypass capacitor between V_{CC} and V_{SS} pins in the vicinity of V_{CC} and V_{SS} pins of the device.



4. Mode Pins (MD0 to MD2)

Connect the mode pins directly to V_{CC} or V_{SS} pins. To prevent the device unintentionally entering test mode due to noise, lay out the printed circuit board so as to minimize the distance from the mode pins to V_{CC} or V_{SS} pins and to provide a low-impedance connection.

5. Sequence for Turning On the Power Supply to the A/D Converter and Analog Inputs

Make sure to turn on the A/D converter power supply (AV_{CC} , $AVRH$, $AVRL$) and analog inputs ($AN0$ to $AN23$) after turning-on the digital power supply (V_{CC}).

Turn-off the digital power after turning off the A/D converter supply and analog inputs. In this case, make sure that the voltage does not exceed $AVRH$ or AV_{CC} (turning on/off the analog and digital power supplies simultaneously is acceptable).

6. Connection of Unused A/D Converter Pins when the A/D Converter is Used

Connect unused pins of A/D converter to $AV_{CC} = V_{CC}$, $AV_{SS} = AVRH = AVRL = V_{SS}$.

7. Crystal Oscillator Circuit

The X0, X1 pins and X0A, X1A pins may be possible causes of abnormal operation. Make sure to provide bypass capacitors via the shortest distance from X0, X1 pins and X0A, X1A pins, crystal oscillator (or ceramic oscillator) and ground lines, and make sure, to the utmost effort, that the oscillation circuit lines do not cross the lines of other circuits. It is highly recommended to provide a printed circuit board art work surrounding X0, X1 pins and X0A, X1A pins with a ground area for stabilizing the operation.

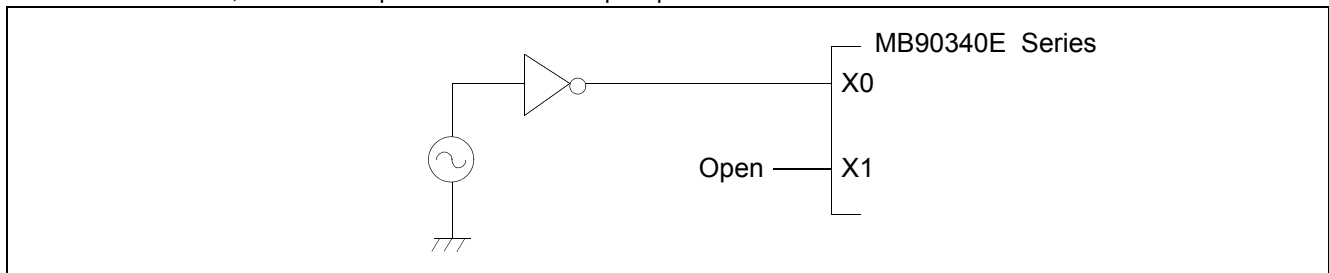
For each of the mass-production products, request an oscillator evaluation from the manufacturer of the oscillator you are using.

8. Pull-up/down resistors

The MB90340E Series does not support internal pull-up/down resistors (except for the pull-up resistors built into ports 0 to 3). Use external components where needed.

9. Using external clock

To use an external clock, drive the X0 pin and leave the X1 pin open.



10. Precautions when not using a sub clock signal

If you do not connect pins X0A and X1A to an oscillator, use pull-down handling on the X0A pin, and leave the X1A pin open.

11. Notes on operation in PLL clock mode

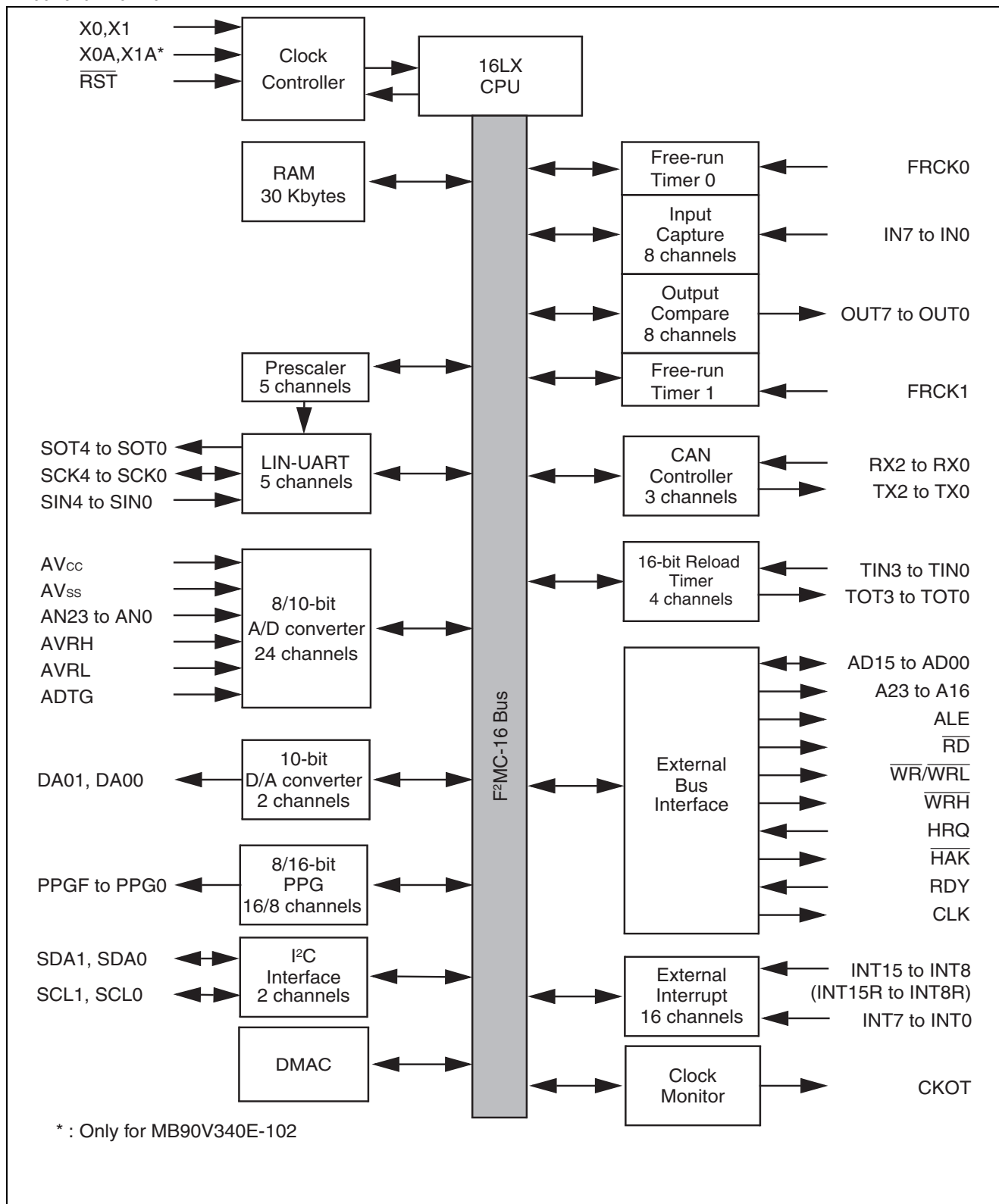
If PLL clock mode is selected, the microcontroller attempt to be working with the self-oscillating circuit even when there is no external oscillator or the external clock input is stopped. Performance of this operation, however, cannot be guaranteed.

12. Notes on Power-On

To prevent the internal regulator circuit from malfunctioning, set the voltage rise time during power-on to 50 μ s or more (0.2 V to 2.7 V)

6. Block Diagrams

■ MB90V340E-101/102



Address	Register	Abbreviation	Access	Resource name	Initial value
0000C4 _H , 0000C5 _H	Reserved				
0000C6 _H	External Interrupt Enable 0	ENIR0	R/W	External Interrupt 0	00000000 _B
0000C7 _H	External Interrupt Source 0	EIRR0	R/W		XXXXXXXX _B
0000C8 _H	External Interrupt Level Setting 0	ELVR0	R/W		00000000 _B
0000C9 _H	External Interrupt Level Setting 0	ELVR0	R/W		00000000 _B
0000CA _H	External Interrupt Enable 1	ENIR1	R/W	External Interrupt 1	00000000 _B
0000CB _H	External Interrupt Source 1	EIRR1	R/W		XXXXXXXX _B
0000CC _H	External Interrupt Level Setting 1	ELVR1	R/W		00000000 _B
0000CD _H	External Interrupt Level Setting 1	ELVR1	R/W		00000000 _B
0000CE _H	External Interrupt Source Select	EISSR	R/W		00000000 _B
0000CF _H	PLL/Sub clock Control Register	PSCCR	W	PLL	XXXX0000 _B
0000D0 _H	DMA Buffer Address Pointer L Register	BAPL	R/W	DMA	XXXXXXXX _B
0000D1 _H	DMA Buffer Address Pointer M Register	BAPM	R/W		XXXXXXXX _B
0000D2 _H	DMA Buffer Address Pointer H Register	BAPH	R/W		XXXXXXXX _B
0000D3 _H	DMA Control Register	DMACS	R/W		XXXXXXXX _B
0000D4 _H	I/O Register Address Pointer L Register	IOAL	R/W		XXXXXXXX _B
0000D5 _H	I/O Register Address Pointer H Register	IOAH	R/W		XXXXXXXX _B
0000D6 _H	Data Counter L Register	DCTL	R/W		XXXXXXXX _B
0000D7 _H	Data Counter H Register	DCTH	R/W		XXXXXXXX _B
0000D8 _H	Serial Mode Register 2	SMR2	W,R/W	UART2	00000000 _B
0000D9 _H	Serial Control Register 2	SCR2	W,R/W		00000000 _B
0000DA _H	Reception/Transmission Data Register 2	RDR2/TDR2	R/W		00000000 _B
0000DB _H	Serial Status Register 2	SSR2	R,R/W		00001000 _B
0000DC _H	Extended Communication Control Register 2	ECCR2	R,W, R/W		000000XX _B
0000DD _H	Extended Status Control Register 2	ESCR2	R/W		00000100 _B
0000DE _H	Baud Rate Generator Register 20	BGR20	R/W		00000000 _B
0000DF _H	Baud Rate Generator Register 21	BGR21	R/W		00000000 _B
0000E0 _H to 0000EF _H	Reserved for CAN Controller 2. Refer to “CAN Controllers”				
0000F0 _H to 0000FF _H	External				

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Address	Register	Abbreviation	Access	Resource name	Initial value
0079E0 _H	Detect Address Setting 0	PADR0	R/W	Address Match Detection 0	XXXXXXXX _B
0079E1 _H	Detect Address Setting 0	PADR0	R/W		XXXXXXXX _B
0079E2 _H	Detect Address Setting 0	PADR0	R/W		XXXXXXXX _B
0079E3 _H	Detect Address Setting 1	PADR1	R/W		XXXXXXXX _B
0079E4 _H	Detect Address Setting 1	PADR1	R/W		XXXXXXXX _B
0079E5 _H	Detect Address Setting 1	PADR1	R/W		XXXXXXXX _B
0079E6 _H	Detect Address Setting 2	PADR2	R/W		XXXXXXXX _B
0079E7 _H	Detect Address Setting 2	PADR2	R/W		XXXXXXXX _B
0079E8 _H	Detect Address Setting 2	PADR2	R/W		XXXXXXXX _B
0079E9 _H to 0079EF _H	Reserved				
0079F0 _H	Detect Address Setting 3	PADR3	R/W	Address Match Detection 1	XXXXXXXX _B
0079F1 _H	Detect Address Setting 3	PADR3	R/W		XXXXXXXX _B
0079F2 _H	Detect Address Setting 3	PADR3	R/W		XXXXXXXX _B
0079F3 _H	Detect Address Setting 4	PADR4	R/W		XXXXXXXX _B
0079F4 _H	Detect Address Setting 4	PADR4	R/W		XXXXXXXX _B
0079F5 _H	Detect Address Setting 4	PADR4	R/W		XXXXXXXX _B
0079F6 _H	Detect Address Setting 5	PADR5	R/W		XXXXXXXX _B
0079F7 _H	Detect Address Setting 5	PADR5	R/W		XXXXXXXX _B
0079F8 _H	Detect Address Setting 5	PADR5	R/W		XXXXXXXX _B
0079F9 _H to 0079FF _H	Reserved				
007A00 _H to 007AFF _H	Reserved for CAN Controller 0. Refer to “CAN Controllers				
007B00 _H to 007BFF _H	Reserved for CAN Controller 0. Refer to “CAN Controllers”				
007C00 _H to 007CFF _H	Reserved for CAN Controller 1. Refer to “CAN Controllers”				
007D00 _H to 007DFF _H	Reserved for CAN Controller 1. Refer to “CAN Controllers”				
007E00 _H to 007FFF _H	Reserved				

Note:

- Initial value of “X” represents unknown value.
- Any write access to reserved addresses in I/O map should not be performed. A read access to reserved addresses results in reading “X”.

10. Interrupt Factors, Interrupt Vectors, Interrupt Control Register

Interrupt cause	EI ² OS Support	DMA channel number	Interrupt vector		Interrupt control register	
			Number	Address	Number	Address
Reset	N	—	#08	FFFFDC _H	—	—
INT9 instruction	N	—	#09	FFFFD8 _H	—	—
Exception	N	—	#10	FFFFD4 _H	—	—
CAN 0 RX	N	—	#11	FFFFD0 _H	ICR00	0000B0 _H
CAN 0 TX/NS	N	—	#12	FFFFCC _H		
CAN 1 RX / Input Capture 6	Y1	—	#13	FFFFC8 _H	ICR01	0000B1 _H
CAN 1 TX/NS / Input Capture 7	Y1	—	#14	FFFFC4 _H		
CAN 2 RX / I ² C0	N	—	#15	FFFFC0 _H	ICR02	0000B2 _H
CAN 2 TX/NS	N	—	#16	FFFFBC _H		
16-bit Reload Timer 0	Y1	0	#17	FFFFB8 _H	ICR03	0000B3 _H
16-bit Reload Timer 1	Y1	1	#18	FFFFB4 _H		
16-bit Reload Timer 2	Y1	2	#19	FFFFB0 _H	ICR04	0000B4 _H
16-bit Reload Timer 3	Y1	—	#20	FFFFAC _H		
PPG 0/1/4/5	N	—	#21	FFFFA8 _H	ICR05	0000B5 _H
PPG 2/3/6/7	N	—	#22	FFFFA4 _H		
PPG 8/9/C/D	N	—	#23	FFFFA0 _H	ICR06	0000B6 _H
PPG A/B/E/F	N	—	#24	FFFF9C _H		
Time Base Timer	N	—	#25	FFFF98 _H	ICR07	0000B7 _H
External Interrupt 0 to 3, 8 to 11	Y1	3	#26	FFFF94 _H		
Watch Timer	N	—	#27	FFFF90 _H	ICR08	0000B8 _H
External Interrupt 4 to 7, 12 to 15	Y1	4	#28	FFFF8C _H		
A/D Converter	Y1	5	#29	FFFF88 _H	ICR09	0000B9 _H
Free-run Timer 0 / Free-run Timer 1	N	—	#30	FFFF84 _H		
Input Capture 4/5 / I ² C1	Y1	6	#31	FFFF80 _H	ICR10	0000BA _H
Output Compare 0/1/4/5	Y1	7	#32	FFFF7C _H		
Input Capture 0 to 3	Y1	8	#33	FFFF78 _H	ICR11	0000BB _H
Output Compare 2/3/6/7	Y1	9	#34	FFFF74 _H		
UART 0 RX	Y2	10	#35	FFFF70 _H	ICR12	0000BC _H
UART 0 TX	Y1	11	#36	FFFF6C _H		
UART 1 RX / UART 3 RX	Y2	12	#37	FFFF68 _H	ICR13	0000BD _H
UART 1 TX / UART 3 TX	Y1	13	#38	FFFF64 _H		

(Continued)

11. Electrical Characteristics

11.1 Absolute Maximum Ratings

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1	V_{CC}	$V_{SS} - 0.3$	$V_{SS} + 6.0$	V	
	AV_{CC}	$V_{SS} - 0.3$	$V_{SS} + 6.0$	V	$V_{CC} = AV_{CC}$ *2
	$AVRH, AVRL$	$V_{SS} - 0.3$	$V_{SS} + 6.0$	V	$AV_{CC} \geq AVRH, AV_{CC} \geq AVRL, AVRH \geq AVRL$
Input voltage*1	V_I	$V_{SS} - 0.3$	$V_{SS} + 6.0$	V	*3
Output voltage*1	V_O	$V_{SS} - 0.3$	$V_{SS} + 6.0$	V	*3
Maximum Clamp Current	I_{CLAMP}	-4.0	+4.0	mA	*5
Total Maximum Clamp Current	$\sum I_{CLAMP} $	—	40	mA	*5
"L" level maximum output current	I_{OL}	—	15	mA	*4, *6
"L" level average output current	I_{OLAV}	—	4	mA	*4, *7
"L" level maximum overall output current	$\sum I_{OL}$	—	100	mA	*4
"L" level average overall output current	$\sum I_{OLAV}$	—	50	mA	*4, *8
"H" level maximum output current	I_{OH}	—	-15	mA	*4, *6
"H" level average output current	I_{OHAV}	—	-4	mA	*4, *7
"H" level maximum overall output current	$\sum I_{OH}$	—	-100	mA	*4
"H" level average overall output current	$\sum I_{OHAV}$	—	-50	mA	*4, *8
Power consumption	P_D	—	450	mW	
Operating temperature	T_A	-40	+105	°C	
Storage temperature	T_{STG}	-55	+150	°C	

*1: This parameter is based on $V_{SS} = AV_{SS} = 0$ V

*2: Set AV_{CC} and V_{CC} to the same voltage. Make sure that AV_{CC} does not exceed V_{CC} and that the voltage at the analog inputs does not exceed AV_{CC} when the power is switched on.

*3: V_I and V_O should not exceed $V_{CC} + 0.3$ V. V_I should not exceed the specified ratings. However if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.

*4: Applicable to pins: P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, PA0, PA1

*5: • Applicable to pins: P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P47, P50 to P57 (Evaluation device : P50 to P55), P60 to P67, P70 to P77, P80 to P87, P90 to P97, PA0 to PA1

• Use within recommended operating conditions.

• Use with DC voltage (current)

• The +B signal should always be applied by using a limiting resistance placed between the +B signal and the microcontroller.

• The value of the limiting resistance should be set so that when the +B signal is applied, the input current to the microcontroller pin does not exceed the rated value, either instantaneously or for prolonged periods.

• Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the V_{CC} pin, and this may affect other devices.

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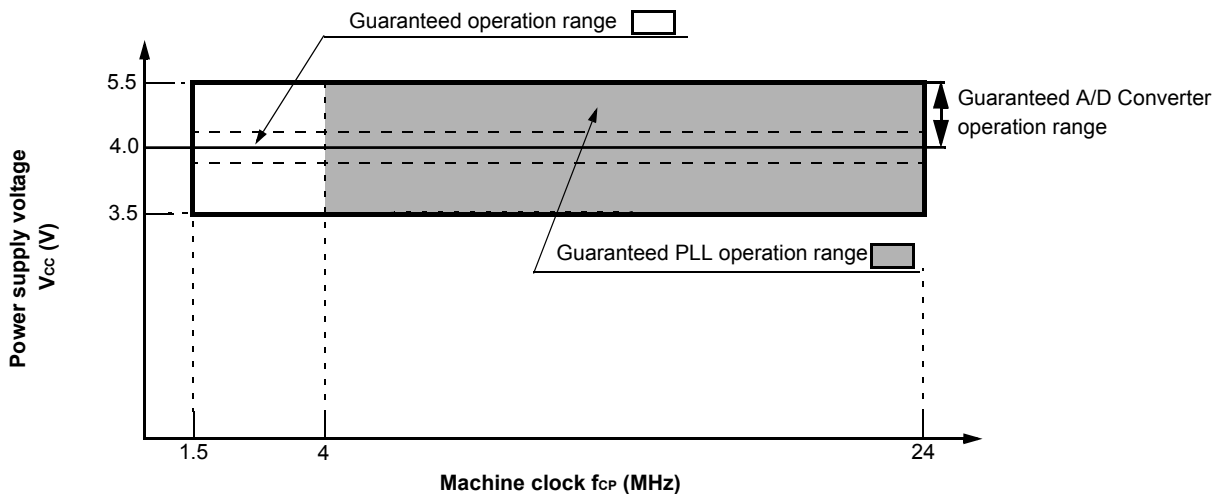
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($T_A = -40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$, $V_{CC} = 5.0\text{ V} \pm 10\%$, $f_{CP} \leq 24\text{ MHz}$, $V_{SS} = AV_{SS} = 0\text{ V}$)

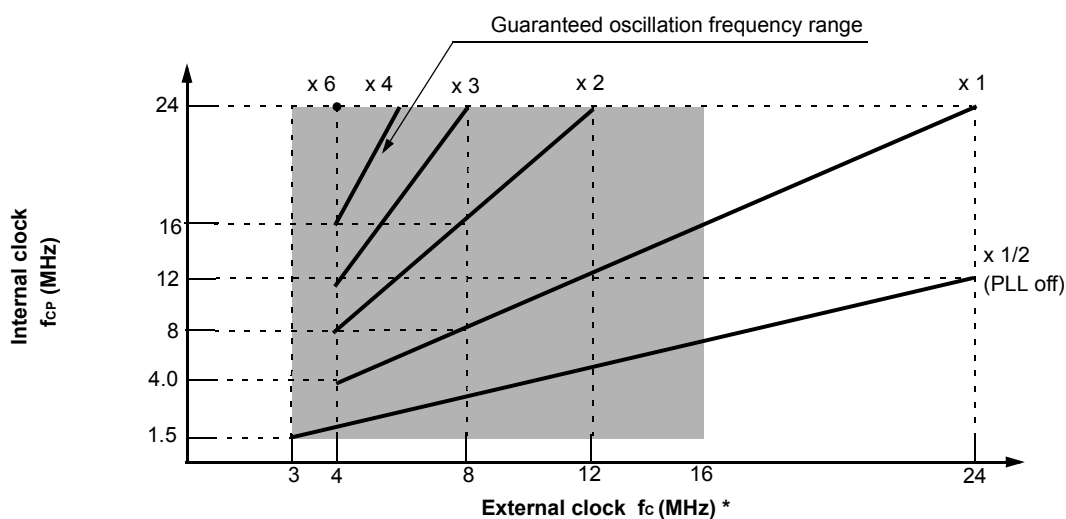
Parameter	Symbol	Pin	Condition	Value			Unit	Remarks
				Min	Typ	Max		
Input leak current	I_{IL}	—	$V_{CC} = 5.5\text{ V}$, $V_{SS} < V_I < V_{CC}$	-1	—	+1	μA	
Pull-up resistance	R_{UP}	P00 to P07, P10 to P17, P20 to P27, P30 to P37, $\overline{\text{RST}}$	—	25	50	100	$\text{k}\Omega$	
Pull-down resistance	R_{DOWN}	MD2	—	25	50	100	$\text{k}\Omega$	Except Flash memory devices
Power supply current*	I_{CC}	V_{CC}	$V_{CC} = 5.0\text{ V}$, Internal frequency : 24 MHz, At normal operation.	—	55	70	mA	
			$V_{CC} = 5.0\text{ V}$, Internal frequency : 24 MHz, At writing Flash memory.	—	70	85	mA	Flash memory devices
			$V_{CC} = 5.0\text{ V}$, Internal frequency : 24 MHz, At erasing Flash memory.	—	75	90	mA	Flash memory devices
	I_{CCS}		$V_{CC} = 5.0\text{ V}$, Internal frequency : 24 MHz, In Sleep mode.	—	25	35	mA	
	I_{CTS}		$V_{CC} = 5.0\text{ V}$, Internal frequency : 2 MHz, In Main Timer mode	—	0.3	0.8	mA	
	$I_{CTSPLL6}$		$V_{CC} = 5.0\text{ V}$, Internal frequency : 24 MHz, In PLL Timer mode, external frequency = 4 MHz	—	4	7	mA	
	I_{CCL}		$V_{CC} = 5.0\text{ V}$ Internal frequency : 8 kHz, In sub operation $T_A = +25^{\circ}\text{C}$	—	70	140	μA	
	I_{CCLS}		$V_{CC} = 5.0\text{ V}$ Internal frequency : 8 kHz, In sub sleep $T_A = +25^{\circ}\text{C}$	—	20	50	μA	
	I_{CCT}		$V_{CC} = 5.0\text{ V}$ Internal frequency : 8 kHz, In watch mode $T_A = +25^{\circ}\text{C}$	—	10	35	μA	
	I_{CCH}		$V_{CC} = 5.0\text{ V}$, In Stop mode, $T_A = +25^{\circ}\text{C}$	—	7	25	μA	
Input capacitance	C_{IN}	Other than C, AV_{CC} , AV_{SS} , $AVRH$, $AVRL$, V_{CC} , V_{SS}	—	—	5	15	pF	

* : The power supply current is measured with an external clock.

Guaranteed PLL operation range



Guaranteed operation range of MB90340E series



* : When using a crystal oscillator or ceramic oscillator, the maximum oscillation clock frequency is 16 MHz

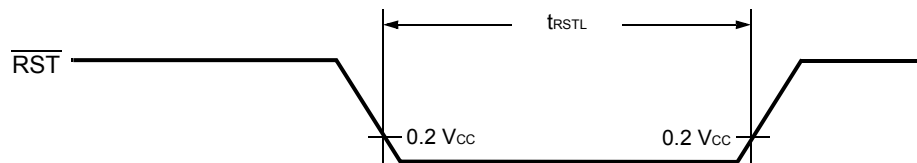
11.4.2 Reset Standby Input

($T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, $V_{CC} = 5.0\text{ V} \pm 10\%$, $f_{CP} \leq 24\text{ MHz}$, $V_{SS} = AV_{SS} = 0.0\text{ V}$)

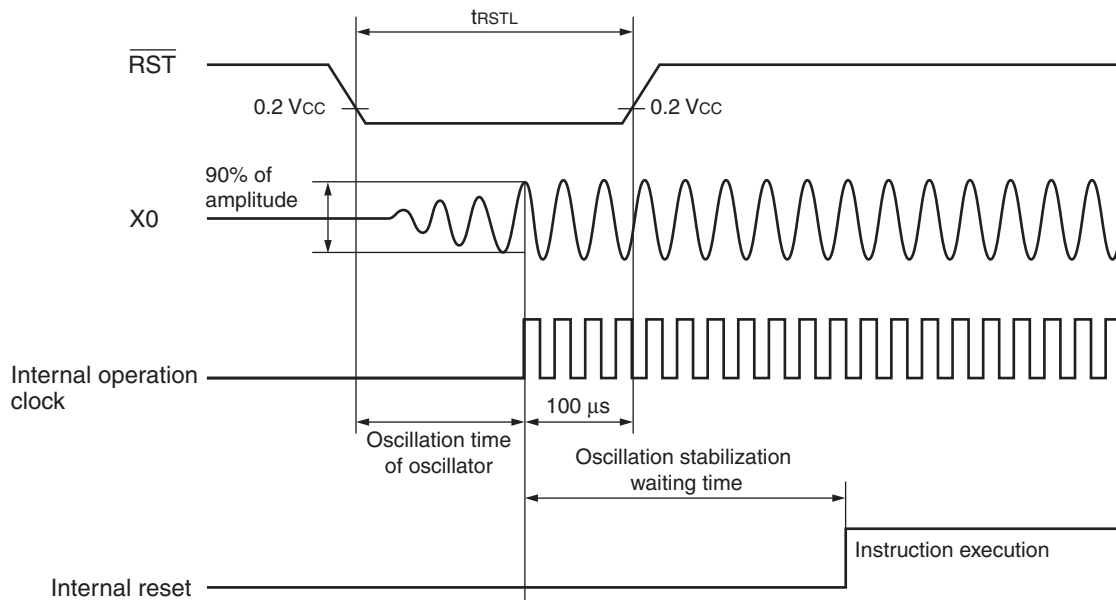
Parameter	Symbol	Pin	Value		Unit	Remarks
			Min	Max		
Reset input time	t_{RSTL}	$\overline{RST}$	500	—	ns	Under normal operation
			Oscillation time of oscillator* + 100 μs	—	μs	In Stop mode, Sub Clock mode, Sub Sleep mode and Watch mode
			100	—	μs	In Time Timer mode

* : The oscillation time of the oscillator is the time it takes for the amplitude of the oscillations to reach 90%. For crystal oscillators, this time is between several ms and several tens of ms, for ceramic oscillators the time is between several hundred μs and several ms, and for an external clock, the time is 0 ms.

● Under normal operation:



● In Stop mode, Sub Clock mode, Sub Sleep mode, Watch mode:



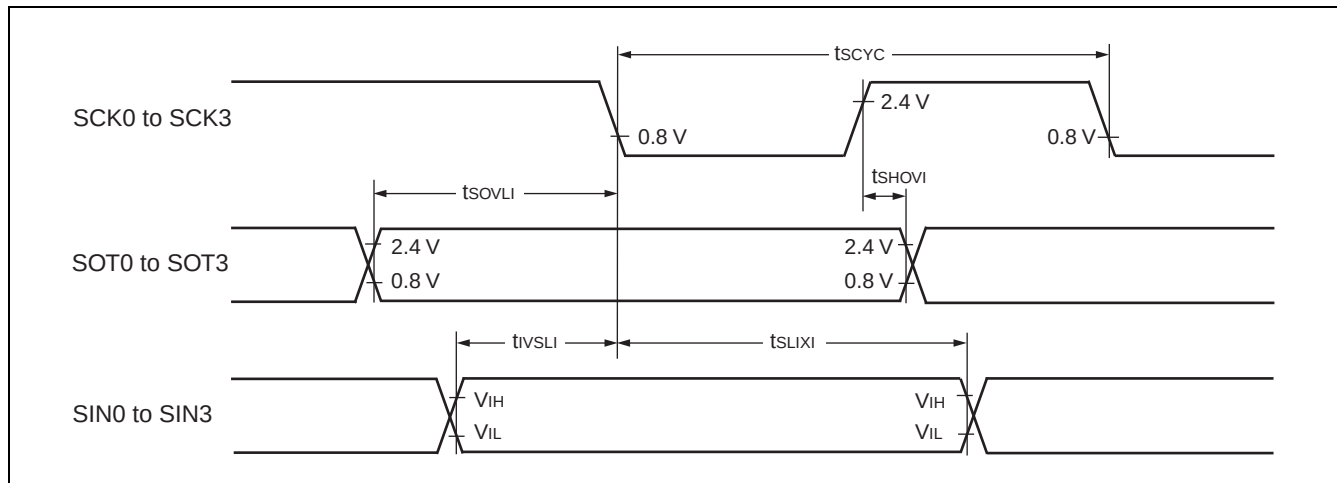
■ Bit setting: ESCR:SCES = 0, ECCR:SCDE = 1

($T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, $V_{CC} = 5.0\text{ V} \pm 10\%$, $f_{CP} \leq 24\text{ MHz}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal clock operation output pins are $C_L = 80\text{ pF} + 1\text{ TTL}$.	$5 t_{CP}$	—	ns
SCK $\uparrow \rightarrow$ SOT delay time	t_{SHOVI}	SCK0 to SCK3, SOT0 to SOT3		-50	+50	ns
Valid SIN $\rightarrow$ SCK $\downarrow$	t_{IVSLI}	SCK0 to SCK3, SIN0 to SIN3		$t_{CP} + 80$	—	ns
SCK $\downarrow \rightarrow$ Valid SIN hold time	t_{SLIXI}	SCK0 to SCK3, SIN0 to SIN3		0	—	ns
SOT $\rightarrow$ SCK $\downarrow$ delay time	t_{SOVLI}	SCK0 to SCK3, SOT0 to SOT3		$3 t_{CP} - 70$	—	ns

Note:

- C_L is load capacity value of pins when testing.
- t_{CP} is internal operating clock cycle time (machine clock) . Refer to “Clock Timing”.



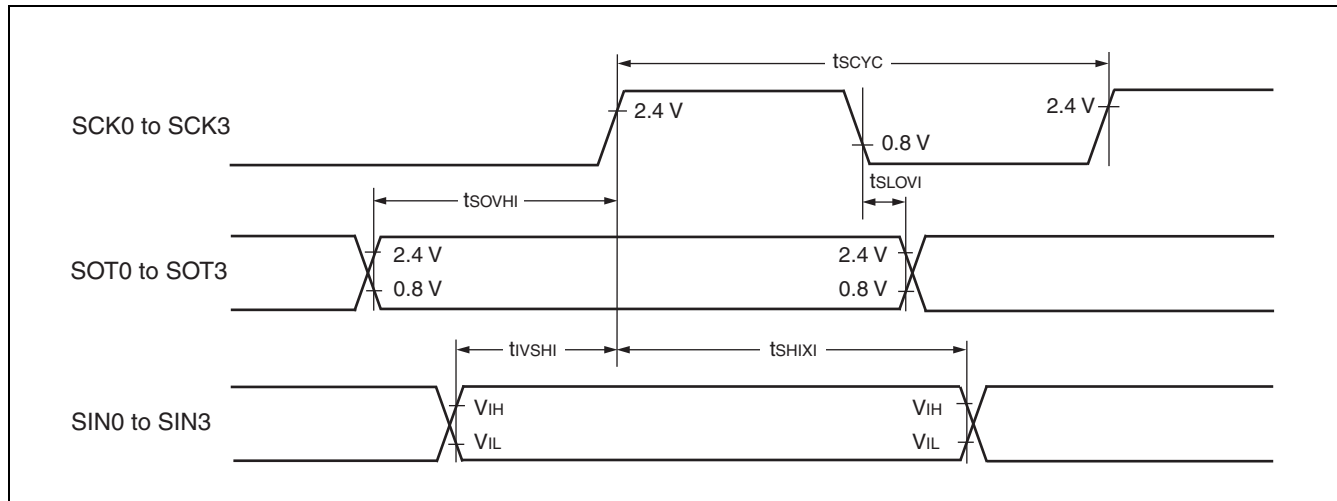
■ Bit setting: ESCR:SCES = 1, ECCR:SCDE = 1

($T_A = -40^\circ\text{C}$ to $+105^\circ\text{C}$, $V_{CC} = 5.0\text{ V} \pm 10\%$, $f_{CP} \leq 24\text{ MHz}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Pin	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK0 to SCK3	Internal clock operation output pins are $C_L = 80\text{ pF} + 1\text{ TTL}$.	$5 t_{CP}$	—	ns
SCK $\downarrow \rightarrow$ SOT delay time	t_{SLOVI}	SCK0 to SCK3, SOT0 to SOT3		-50	+50	ns
Valid SIN $\rightarrow$ SCK $\uparrow$	t_{IVSHI}	SCK0 to SCK3, SIN0 to SIN3		$t_{CP} + 80$	—	ns
SCK $\uparrow \rightarrow$ Valid SIN hold time	t_{SHIXI}	SCK0 to SCK3, SIN0 to SIN3		0	—	ns
SOT $\rightarrow$ SCK $\uparrow$ delay time	t_{SOVHI}	SCK0 to SCK3, SOT0 to SOT3		$3 t_{CP} - 70$	—	ns

Note:

- C_L is load capacity value of pins when testing.
- t_{CP} is internal operating clock cycle time (machine clock) . Refer to “Clock Timing”.



11.4.13 I²C Timing

(T_A = -40°C to +105°C, V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V)

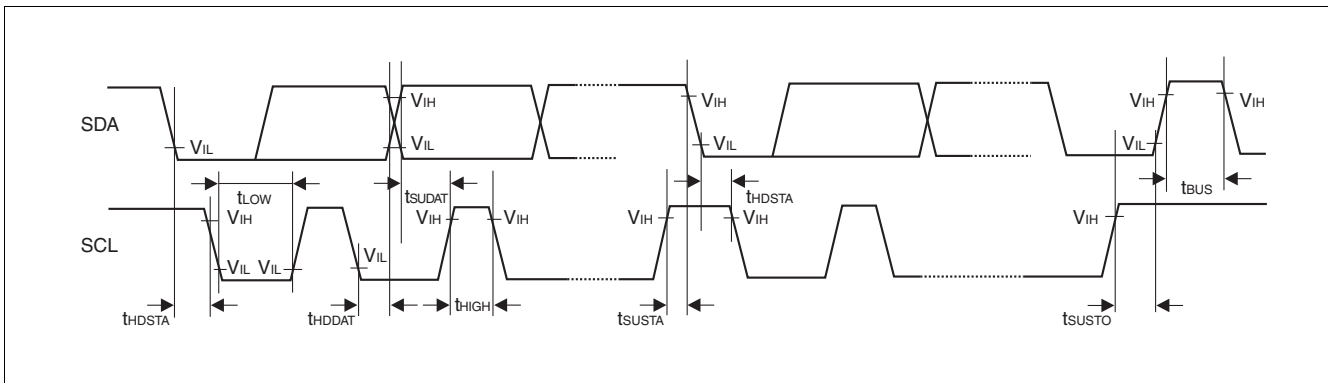
Parameter	Symbol	Condition	Standard-mode		Fast-mode* ¹		Unit
			Min	Max	Min	Max	
SCL clock frequency	f _{SCL}	R = 1.7 kΩ ₂ C = 50 pF* ²	0	100	0	400	kHz
Hold time (repeated) START condition SDA ↓ → SCL ↓	t _{HDSTA}		4.0	—	0.6	—	μs
"L" width of the SCL clock	t _{LOW}		4.7	—	1.3	—	μs
"H" width of the SCL clock	t _{HIGH}		4.0	—	0.6	—	μs
Set-up time (repeated) START condition SCL ↑ → SDA ↓	t _{SUSTA}		4.7	—	0.6	—	μs
Data hold time SCL ↓ → SDA ↓ ↑	t _{HDDAT}		0	3.45* ³	0	0.9* ⁴	μs
Data set-up time SDA ↓ ↑ → SCL ↑	t _{SUDAT}		250	—	100	—	ns
Set-up time for STOP condition SCL ↑ → SDA ↑	t _{SUSTO}		4.0	—	0.6	—	μs
Bus free time between a STOP and START condition	t _{BUS}		4.7	—	1.3	—	μs

*1: For use at over 100 kHz, set the machine clock to at least 6 MHz.

*2: R, C: Pull-up resistor and load capacitor of the SCL and SDA lines.

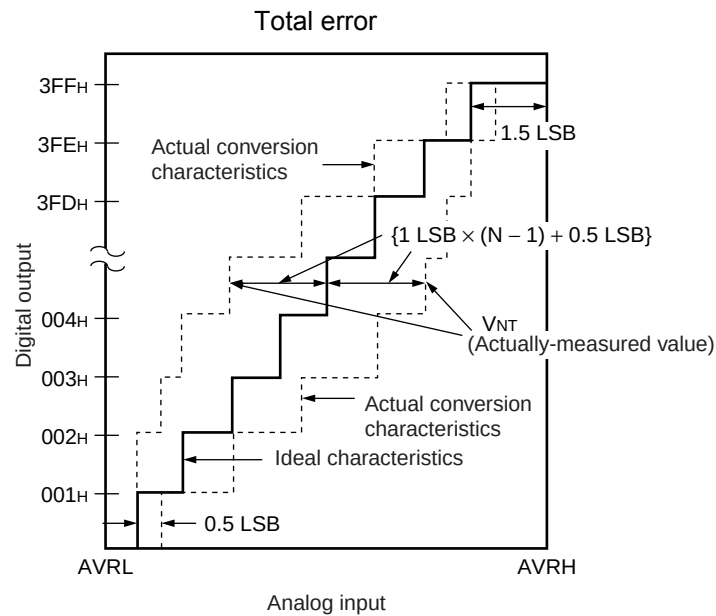
*3: The maximum t_{HDDAT} meets the requirement that it does not extend the "L" width (t_{LOW}) of the SCL signal.

*4: A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system, but the requirement t_{SUDAT} ≥ 250 ns must then be met.



11.6 Definition of A/D Converter Terms

- Resolution : Analog variation that is recognized by the A/D converter.
- Non linearity error : The deviation between the actual conversion characteristics and a line that joins the zero-transition line ("00 0000 0000" $\leftrightarrow$ "00 0000 0001") to the full-scale transition line ("11 1111 1110" $\leftrightarrow$ "11 1111 1111").
- Differential linearity error : Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
- Total error : Difference between the actual value and the ideal value. The total error includes zero transition error, full-scale transition error, and linear error.



$$\text{Total error of digital output "N"} = \frac{V_{NT} - \{1 \text{ LSB} \times (N - 1) + 0.5 \text{ LSB}\}}{1 \text{ LSB}} \text{ [LSB]}$$

$$1 \text{ LSB (Ideal value)} = \frac{AVRH - AVRL}{1024} \text{ [V]}$$

N : Value of the digital output from the A/D converter

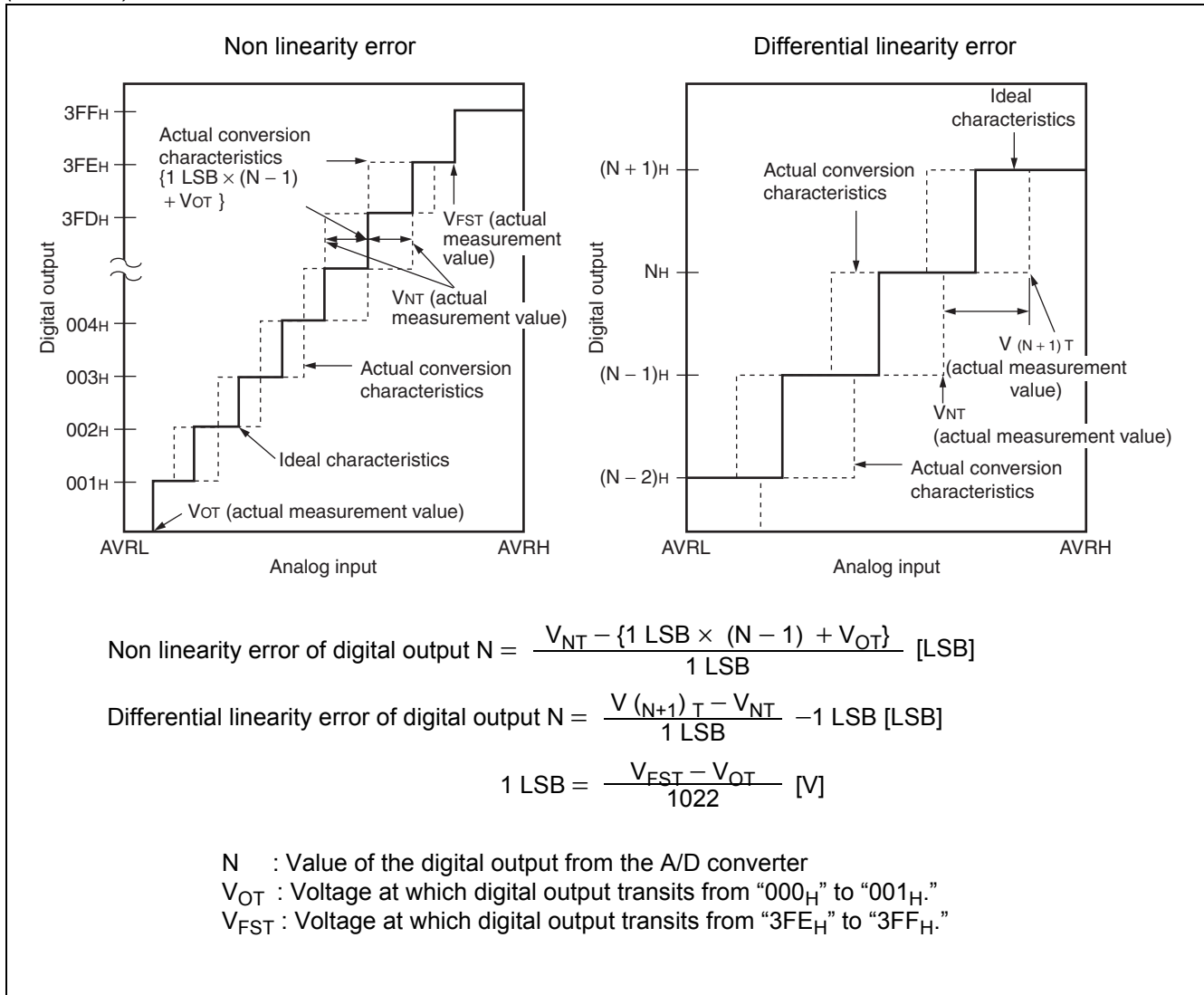
$$V_{OT} \text{ (Ideal value)} = AVRL + 0.5 \text{ LSB [V]}$$

$$V_{FST} \text{ (Ideal value)} = AVRH - 1.5 \text{ LSB [V]}$$

V_{NT} : A voltage at which the digital output transitions from $(N - 1)_H$ to N_H .

(Continued)

(Continued)



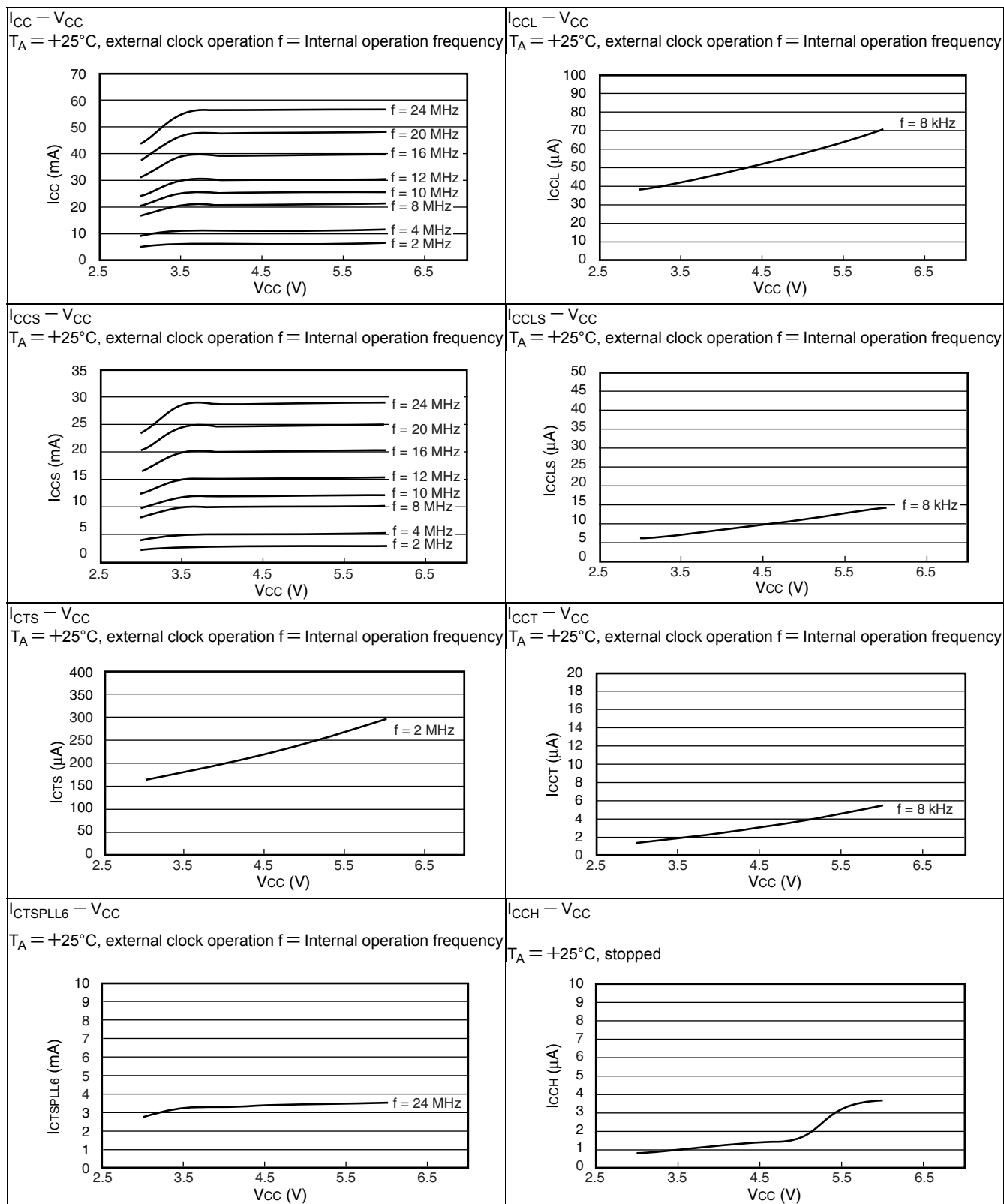
11.7 Notes on A/D Converter Section

Use the device with external circuits of the following output impedance for analog inputs :

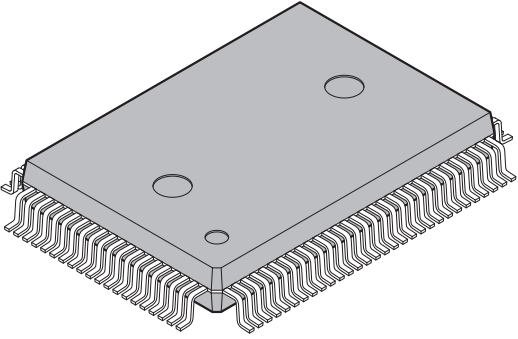
Recommended output impedance of external circuits are : Approx. 1.5 kΩ or lower (4.0 V ≤ AV_{CC} ≤ 5.5 V,
sampling period = 0.5 μs)

If an external capacitor is used, in consideration of the capacitive voltage dividing effect between the external capacitor and the internal on-chip capacitor, it is recommended that the capacitance of the external capacitor be several thousand times greater than the capacitance of the internal capacitor.

■ MB90F342E, MB90F342ES, MB90F342CE, MB90F342CES



(Continued)

100-pin plastic QFP  (FPT-100P-M06)	Lead pitch	0.65 mm
	Package width × package length	14.00 × 20.00 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	3.35 mm MAX
	Code (Reference)	P-QFP100-14×20-0.65

